

Sensors and Materials

Special Issue on

Materials, Devices, Circuits, and Analytical Methods for Various Sensors

(Selected Papers from ICSEVEN 2021)

Call for Papers

The era of ubiquitous sensing has begun recently thanks to the rapid development of IoT. Sensors are essential components of automotive electronic systems used in modern applications including smart industries, smart cities, smart cars, robots, smart buildings, and smart homes. This issue will focus on all aspects of research and development related to sensor materials, sensor devices, sensor circuits, sensor readout circuits, sensor modules, sensor sub-systems, systems, analytical software, deep learning, and artificial intelligence (AI) for sensor and material applications.

We invite authors to contribute original research as well as comprehensive review articles on the recent progress in materials, devices, circuits, analytical methods, and applications related to various sensors. Potential topics include, but are not limited to:

- Sensor materials
- Sensor devices and sensor arrays/nanosensors/MEMS sensors
- Electrochemical sensors
- Microwave sensors
- Sensor applications for industry, medicine, bio-signal monitoring, environmental monitoring, corrosion, etc.
- Analytical methods, modeling, readout circuits and software for various sensors
- Deep learning and AI for sensor and material applications.
- Sensor technology and new sensor principles
- Sensor technology applications and innovative issues related to management

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